



HSDF880

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HSDF880 is designed for audio frequency power amplifier applications.

Features

- High DC Current Gain.
- High Power Dissipation : PC=30W at Tc=25°C

Absolute Maximum Ratings (Ta=25°C)

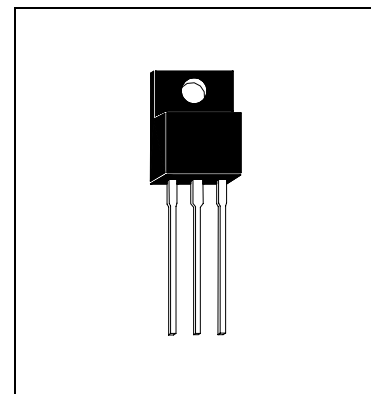
- Maximum Temperatures
Storage Temperature -50~+150°C
Junction Temperature +150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 20 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 60 V
BVCEO Collector to Emitter Voltage 60 V
BVEBO Emitter to Base Voltage 7 V
IC Collector Current 3 A
IB Base Current 0.5 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	60	-	-	V	IC=50mA, IE=0
ICBO	-	-	0.1	mA	VCB=60V, IE=0
IEBO	-	-	0.1	mA	VEB=7V, IC=0
VCE(sat)	-	-	1	V	IC=3A, IB=0.3A
VBE(on)	-	-	1.0	V	IC=0.5A, VCE=5V
hFE	60	-	300		IC=0.5A, VCE=5V
fT	-	3	-	MHz	VCE=5V, IC=500mA

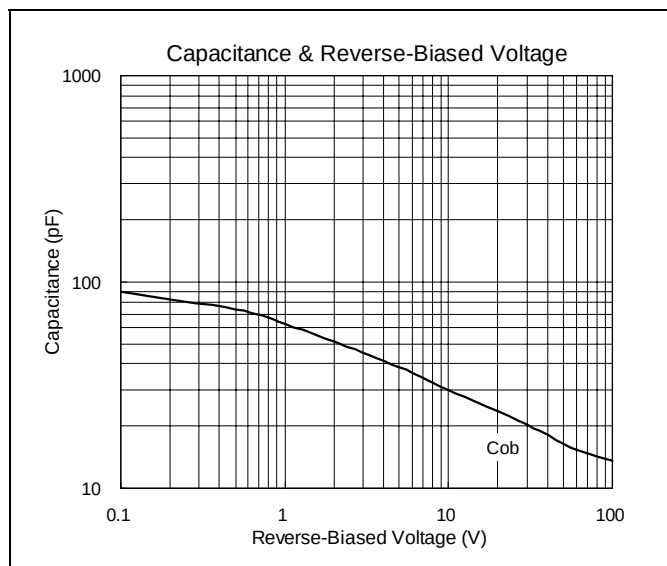
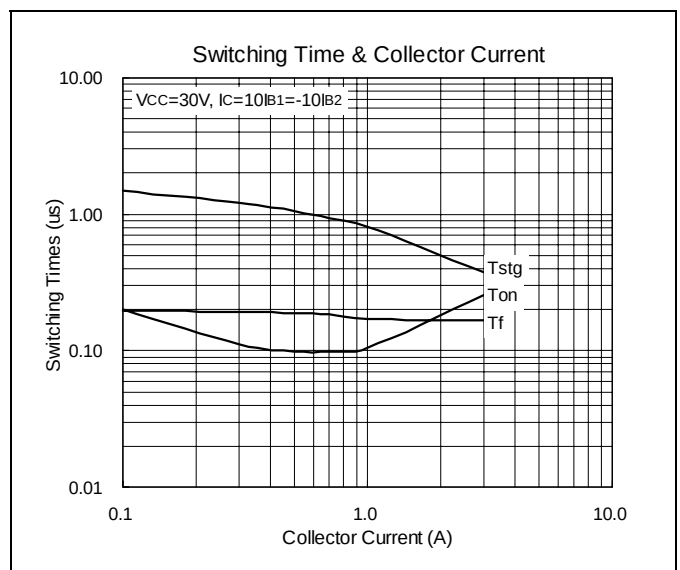
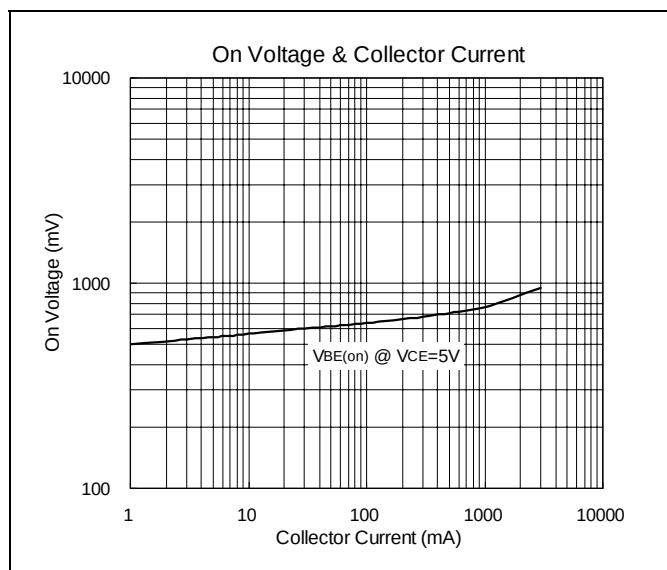
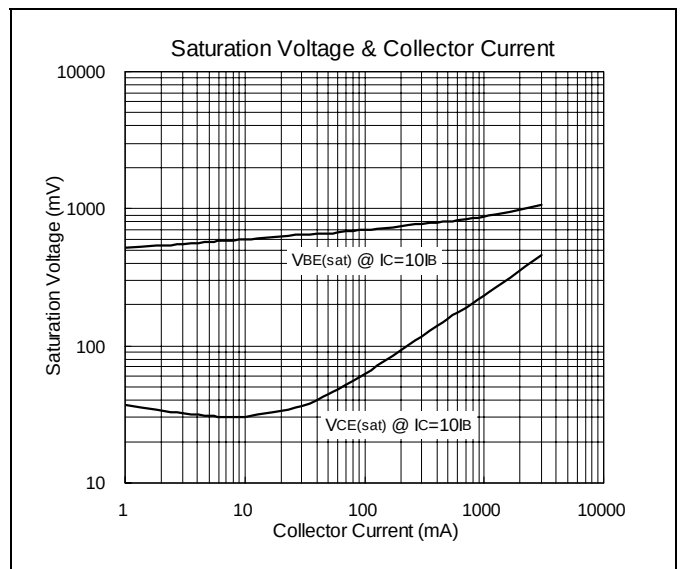
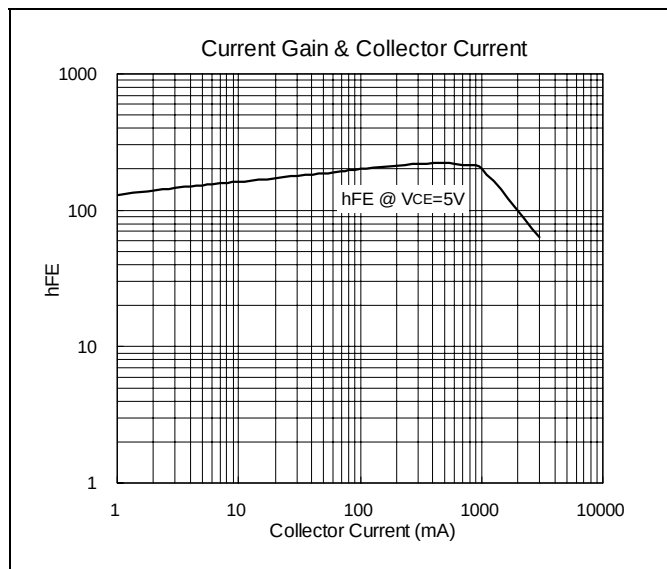
Classification Of hFE

Rank	O	Y	GR
Range	60-120	100-200	150-300



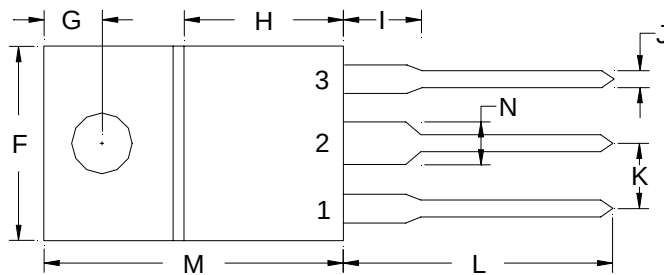
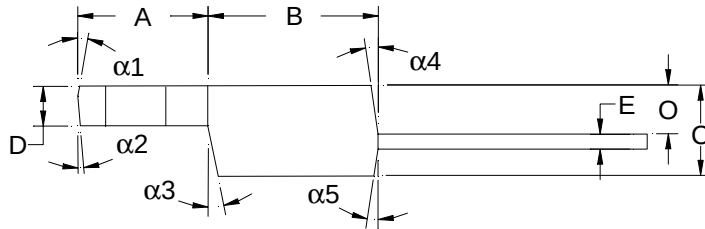


Characteristics Curve



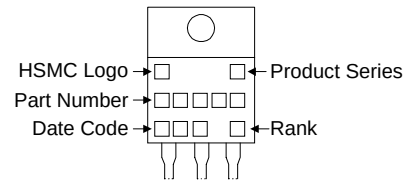


TO-220FP Dimension



3-Lead TO-220FP Plastic Package
HSMC Package Code : F

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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